

(b) a dielectric element overlying said chip front surface, said dielectric element having a first surface facing toward said chip and a second surface facing away from said chip;

(c) a plurality of terminals disposed on said dielectric element for interconnection to a substrate and overlying said chip front surface, said terminals being electrically connected to said central contacts and being movable with respect to said central contacts so as to compensate for thermal expansion of said chip.

Cont'd  
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<sup>13</sup>  
73. A chip assembly as claimed in claim <sup>12</sup>72, wherein said dielectric element includes a thin, flexible layer formed from a material selected from the group consisting of thermoset and thermoplastic polymers and defining said second surface of said dielectric element.

<sup>14</sup>  
74. A chip assembly as claimed in claim <sup>12</sup>72, wherein said dielectric element includes a sheet-like, electrically conductive grounding layer.

<sup>15</sup>  
75. A chip assembly as claimed in claim <sup>12</sup>72, wherein said plurality of terminals are disposed at said second surface of said dielectric element.

<sup>16</sup>  
76. A chip assembly as claimed in claim <sup>12</sup>72 wherein said dielectric element includes a compliant layer disposed between said terminals and said front surface of said chip.

#### REMARKS

The present preliminary amendment presents new claims 71-76, in addition to previously allowed claims 61-70. The new claims are supported, *inter alia*, by the disclosure at page 47, lines 3-33 and Fig. 18 of the present specification. New dependent claim 71 specifies that the central contact leads include wire bonds, as set forth in page 47, lines 28-31 of the specification. New claim 72 is similar to allowed


claim 61 in that claim 72 also recites the central location of the contact on the chip. New claim 72 states the connection between these contacts and the terminals on the dielectric element in different terms than claim 61.

An Information Disclosure Statement is enclosed. United States Patents 5,055,913 and 4,897,534, cited in the Information Disclosure Statement, do not have terminals overlying the chip surface, but instead have terminals disposed outboard of the chip.

Thus, Applicants earnestly solicit allowance of new claims 71-76 in addition to the previously allowed claims. If there are any additional fees due in connection with this preliminary amendment, the Examiner is hereby authorized to charge such fees to Deposit Account No. 12-1095.

Respectfully Submitted,

LERNER, DAVID, LITTENBERG,  
KRUMHOLZ & MENTLIK, LLP

  
MARCUS J. MILLET  
Reg. No. 28,241

600 South Avenue West  
Westfield, New Jersey 07090  
Tel: (908) 654-5000  
Fax: (908) 654-7866

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